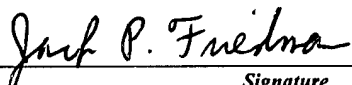
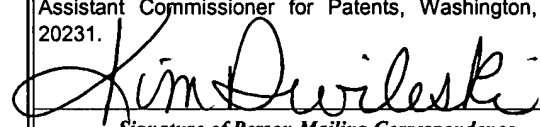


CAU 2822

TRANSMITTAL LETTER (General - Patent Pending)		Docket No. EN9-98-141	
In Re Application Of: Sebesta et al. AUG 31 2001			
Serial No. 09/526,957	Filing Date 3/16/00	Examiner Mitchell, J.	Group Art Unit 2822
Title: VARIABLE THICKNESS PADS ON A SUBSTRATE SURFACE			
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>			
Transmitted herewith is: Amendment			
in the above identified application.			
<input checked="" type="checkbox"/> No additional fee is required.			
<input type="checkbox"/> A check in the amount of _____ is attached.			
<input checked="" type="checkbox"/> The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below. A duplicate copy of this sheet is enclosed.			
<input type="checkbox"/> Charge the amount of _____			
<input checked="" type="checkbox"/> Credit any overpayment.			
<input checked="" type="checkbox"/> Charge any additional fee required.			
 _____ Signature		Dated: 8/29/01	
Jack P. Friedman Reg. No. 44,688 Schmeiser, Olsen & Watts 3 Lear Jet Lane, Suite 201 Latham, NY 12110 (518) 220-1850		<div style="border: 1px solid black; padding: 5px;"><p>I certify that this document and fee is being deposited on 8/29/01 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.</p><p> Signature of Person Mailing Correspondence</p><p style="text-align: center;">Kim Dwileski Typed or Printed Name of Person Mailing Correspondence</p></div>	
CC:			



DOCKET NO. EN9-98-141

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SEP - 5 2001

Handwritten notes:
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F. Bell
9.6.01
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3.19.02
Bell.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Sebesta *et al.*

Examiner: Mitchell, J.

Serial No.: 09/526,957

Art Unit: 2822

Filed: 3/16/00

For: **VARIABLE THICKNESS PADS ON A SUBSTRATE SURFACE**

Commissioner for Patents
Washington D.C. 20231

Sir:

This paper is being filed in response to the Final Office Action mailed July 5, 2001.

Applicants respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

Amendment

Please amend the above-referenced patent application as follows:

In The Claims

The following claims 1-13 are currently pending.

1. (AMENDED) An electronic structure, comprising:

a substrate;

a first circuit line including a first conductive pad and having a first thickness, wherein the first circuit line is coupled to the substrate and is not embedded into the substrate; and

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